



UL 746B

Zytel® HTNFR52G45NHF NC010 (PRELIMINARY) HIGH PERFORMANCE POLYAMIDE RESIN

Zytel® HTNFR52G45NHF NC010 is a 45% Glass Reinforced, Flame Retardant, High Performance Polyamide with improved flow. It is also a PPA resin and it uses a non-halogenated flame retardant.

Product information

Resin Identification	PA6T/66-GF45FR(40)	ISO 1043
Part Marking Code	>PA6T/66-GF45FR(40)<	ISO 11469
Part Marking Code	>PPA-GF45FR<	SAE J1344
ISO designation	ISO 16396-PA6T/66,GF45 FR(40),M1F1GN,S10-160	

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Rheological properties	dry/cond.		
Moulding shrinkage, parallel	0.2/-	%	ISO 294-4, 2577
Moulding shrinkage, normal	0.6/-	%	ISO 294-4, 2577
Typical mechanical properties	dry/cond.		
	•	.45	100 507 440
Tensile modulus	15500/-	MPa	ISO 527-1/-2
Tensile stress at break, 5mm/min	167/-	MPa	ISO 527-1/-2
Tensile strain at break, 5mm/min	1.7/-	%	ISO 527-1/-2
Flexural modulus	15100/-	MPa	ISO 178
Flexural strength	250/-	MPa	ISO 178
Charpy impact strength, 23°C	48/-	kJ/m²	ISO 179/1eU
Charpy impact strength, -30°C	45/-	kJ/m²	ISO 179/1eU
Charpy notched impact strength, 23°C	8/-	kJ/m²	ISO 179/1eA
Charpy notched impact strength, -30°C	8/-	kJ/m²	ISO 179/1eA
Poisson's ratio	0.33/-		
Thermal properties	dry/cond.		
Melting temperature, 10 ° C/min	310/*	°C	ISO 11357-1/-3
Melting temperature, first heat	310/*	°C	ISO 11357-1/-3
Glass transition temperature, 10°C/min	90/45	°C	ISO 11357-1/-3
Temperature of deflection under load, 1.8 MPa	284/*	°C	ISO 75-1/-2
Coeff. of linear therm. expansion, parallel, -40-23°C	13/*	E-6/K	ISO 11359-1/-2
Coefficient of linear thermal expansion	15/*	E-6/K	ISO 11359-1/-2
(CLTE), parallel			
Coeff. of linear therm. expansion, parallel, 55-160°C	14/*	E-6/K	ISO 11359-1/-2
Coeff. of linear therm. expansion, normal, -40-23°C	43/*	E-6/K	ISO 11359-1/-2
Coefficient of linear thermal expansion (CLTE), normal	50/*	E-6/K	ISO 11359-1/-2
Coeff. of linear therm. expansion, normal, 55-160°C	80/*	E-6/K	ISO 11359-1/-2

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140

140

140

140

125

130

125/*

°C

°C

°C

°C

°C

°C

°C

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RTI, electrical, 0.4mm

RTI, electrical, 0.75mm

RTI, electrical, 1.5mm

RTI, electrical, 3.0mm

RTI, strength, 0.75mm

RTI, strength, 1.5mm

RTI, strength, 3.0mm





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Flammability	dry/cond.		
Burning Behav. at thickness h	V-0/*	class	IEC 60695-11-10
Thickness tested	0.4/*	mm	IEC 60695-11-10
UL recognition	yes/*		UL 94
Glow Wire Flammability Index, 0.4mm	960/-	°C	IEC 60695-2-12
Glow Wire Flammability Index, 0.75mm	960/-	°C	IEC 60695-2-12
Glow Wire Flammability Index, 1.5mm	960/-	°C	IEC 60695-2-12
Glow Wire Flammability Index, 3.0mm	960/-	°C	IEC 60695-2-12
Glow Wire Ignition Temperature, 0.75mm	750/-	°C	IEC 60695-2-13
Glow Wire Ignition Temperature, 0.4mm	700/-	°C	IEC 60695-2-12
Glow Wire Ignition Temperature, 1.5mm	750/-	°C	IEC 60695-2-13
Glow Wire Ignition Temperature, 3.0mm	800/-	°C	IEC 60695-2-13
Electrical properties	dry/cond.		
Relative permittivity, 100Hz	4.7/-		IEC 62631-2-1
Relative permittivity, 1MHz	4.4/-		IEC 62631-2-1
Dissipation factor, 100Hz	60/-	E-4	IEC 62631-2-1
Dissipation factor, 1MHz	115/-	E-4	IEC 62631-2-1
Volume resistivity	>1E13/-	Ohm.m	IEC 62631-3-1
Electric strength	40/-	kV/mm	IEC 60243-1
Comparative tracking index	600/-		IEC 60112
Physical/Other properties	dry/cond.		
Density	1600/-	kg/m³	ISO 1183
Injection			

Drying Recommended	yes	
Drying Temperature	100	°C
Drying Time, Dehumidified Dryer	6 - 8	h
Processing Moisture Content	≤0.1	%
Min. melt temperature	320	°C
Max. melt temperature	325	°C
Min. mould temperature	90	°C
Max. mould temperature	130	°C

Characteristics

Processing Injection Moulding

Flame retardant, Non-halogenated/Red phosphorous free flame retardant Additives

Flame retardant, Lead-free soldering resistant Special characteristics

Additional information

Injection molding For molding machine components, use corrosion resistant and wear resistant

> steel. For details please contact our representative. Limit the residence time of the resin in the machine. Use proper protective equipment and adequate

ventilation.

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The above data are preliminary and are subject to change as additional data are developed on subsequent lots.

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